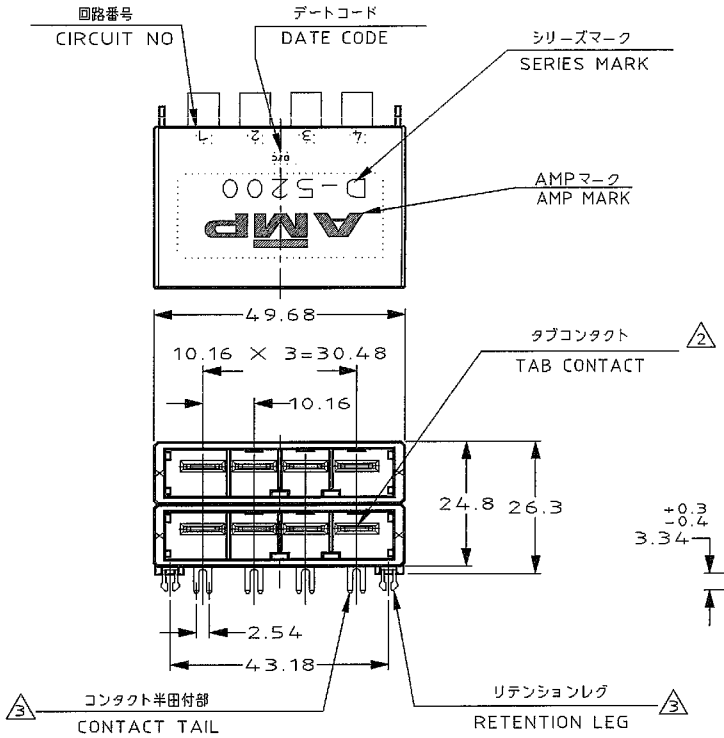
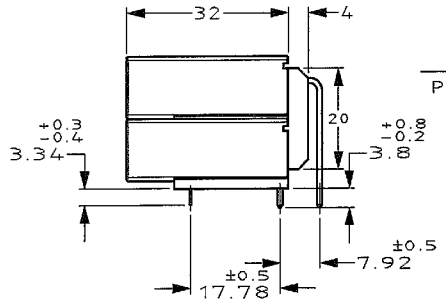
NUMBER 1123829

3rd ANGLE PROJECTION

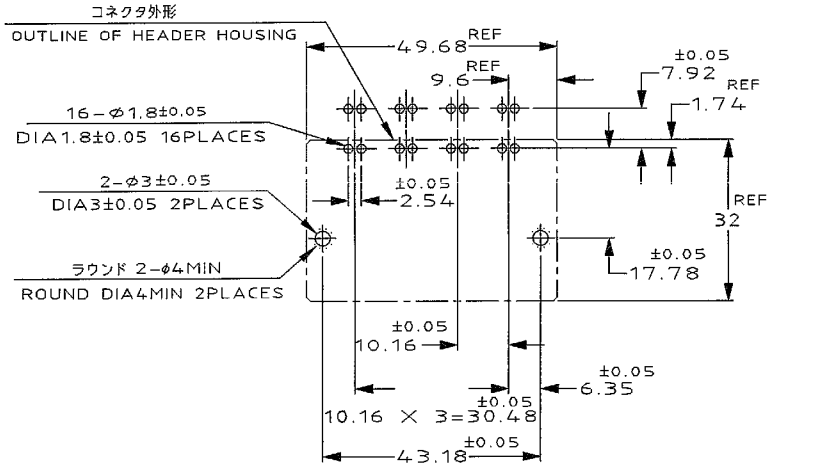
METRIC





— 1:本図

-1:AS SHOWN

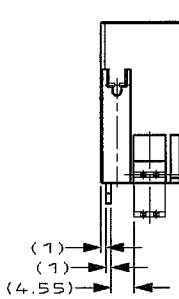


推奨基板取付け穴寸法

PC 基板厚:1.6～2.4±0.1
(非累積公差)
(コネクタ搭載面)

RECOMENDED PC BOARD HOLE PATTERN

PC BOARD THICKNESS:1.6～2.4±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)



NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC
,POLYESTER(94V-0),COLOR:BLACK
TAB CONTACT:COPPER ALLOY
RETENTION LEG:BRASS

2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING
OVER Ni PLATING

3. FINISH(RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

PRODUCT SPEC. 108-5453

注 記

1. 材料: ハウジング: ガラス入り熱可塑性
ポリエステル樹脂 (94V-0),色: 黒
タブ コンタクト: 銅合金
リテンション レグ: 黄銅

2. めっき: コンタクト: 全面Ni下地
接触部: 0.38μm MIN金めっき

3. めっき: リテンションレグとコンタクト半田付部
: ニッケル下地の上にスズめっき

LTR	REVISION RECORD	DR	CHK	DATE
D	REVISED (FJ00-0039-03)	TS	SM	8/2 '03
C	REVISED (FJ00-1758-98)	MH	NM	9/14 '98
B	REVISED (FJ00-1390-98)	MH	NM	8/5 '98
A	REVISED (FJ00-1336-98)	MH	NM	7/13 '98
0	RELEASED(FJ00-0668-98)	MH	NM	6/15 '98

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tyco Electronics | Tyco Electronics AMP K.K. Kawasaki,Japan

WIRE RANGE	mm²(AWG -)
INSULATION DIA	- mmφ
MATERIAL	SEE NOTE 注記参照
FINISH	SEE NOTE 注記参照
DR.	15JUN'98 M.HIGO
DE.	15JUN'98 M.HIGO
CHK.	15JUN'98 N.MATSUBARA
APP.	15JUN'98 I.HASEGAWA

NAME (8極 2列 水平タイプ ヘッダー アッシー)

8 POS DOUBLE ROW HORIZONTAL HDR ASS'Y
<DYNAMIC D-5200>

一般公差 (GENERAL TOLERANCE)
10以下 ±0.3
10を超え 30以下 ±0.35
30を超え100以下 ±0.4
角度 ±3°

SIZE	LOC	NUMBER
A3	J	C-1123829

SCALE	REV.	SHEET
1-1	D	1 OF 1

CAPI=OLD=E18296=U.DYNAMIC>>S.1123829.C.1.C
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J
REV.10/'83

(CUSTOMER DRAWING) 顧 客 用 図 面